

CRYSTAL OSCILLATOR **OUTPUT: CMOS**







Product Number

SG2016CBA: X1G006311xxxx15 SG2520CBA: X1G006301xxxx15

SG2016CBA / SG2520CBA

: 5 standard frequencies (75 MHz to 170 MHz)

: 1.62 V to 3.63 V • Supply voltage

: Output enable (OE/ $\overline{\text{OE}}$) or Standby ($\overline{\text{ST}}/\text{ST}$) Function

: $\pm 15 \times 10^{-6}$ (-40 °C to +105 °C) • Frequency tolerance

±25 × 10⁻⁶, ±50 × 10⁻⁶ (-40 °C to +125 °C)

 $2.0 \times 1.6 \times 0.6 \text{ mm}$: 0.3 ps Typ., 0.6 ps Max. (Offset frequency: 12 kHz to 20 MHz)

• Phase jitter • Utilizing Epson's low noise Integer-N PLL technology

AEC-Q100 compliant



SG2016CBA



Specifications (characteristics)									
Item	Symbol	Specifications		Conditions/Remarks					
Cumply voltage	\/	1.80 V Typ.	2.5	50 V Typ.	3.30 V Typ.				
Supply voltage	V _{CC}	1.62 V to 1.98 V	2.25	V to 2.75 V	2.97 V to 3.63 V				
	fo	75 MHz to 170 MHz				Please contact us for frequency other than the standard frequencies.			
Output frequency range		76.8 MHz, 100 MHz, 125 MHz,				Standard frequencies.			
Storage temperature	Tota	150 MHz, 156.25 MHz				·			
Storage temperature	T_stg	-55 °C to +125 °C			Storage as single product	•			
Operating temperature	T_use	H: -40 °C to +105 °C J: -40 °C to +125 °C							
		J: -40		±15 × 10 ⁻⁶		Includes 1 year aging			
		B:			20 × 10 ⁻⁶	Includes 1 year aging T_use = -40 °C to +		°C to +105 °C	
						Includes 10 years aging			
Frequency tolerance*1	f_tol	D:		±25 × 10 ⁻⁶		Includes 1 year aging	T_use = -40 °C to +125 °C		
					30 × 10 ⁻⁶	Includes 10 years aging			
		J:		±50 × 10 ⁻⁶		Includes 1 year aging	T use = -40 °C to +125 °C		
			Į.	±	55 × 10 ⁻⁶	Includes 10 years aging	_		
		6.8 mA Typ.	7.6	6 mA Typ.	8.7 mA Typ.	-75 MHz ≤ fo ≤ 100 MHz			
		9.1 mA Max.	10.2	2 mA Max.	11.6 mA Max.		No load		
Current consumption	Icc	7.6 mA Typ.	8.7	7 mA Typ.	10.0 mA Typ.	100 MHz < fo≤ 125 MHz			
Current consumption	100	9.8 mA Max.	11.3 mA Max.		13.2 mA Max.	TOO IVII IZ > IO = 120 IVIITZ	No load		
		8.6 mA Typ.	10.1 mA Typ.		12.3 mA Typ.	125 MHz < fo≤ 170 MHz			
		12.0 mA Max.	13.9 mA Max.		16.6 mA Max.	120 IVII 12 > 10 = 17 0 IVII 12			
Output disable current	I_dis	6.1 mA Typ.	o. 6.2 mA Typ.		6.3 mA Typ.	OE = GND OE = V _{CC}			
		10.0 mA Max.	. 10.0 mA Max.		10.0 mA Max.				
Standby ourrant	I_std	0.3 μA Typ.	0.4 μA Typ.		0.5 μA Typ.	ST = GND ST = V _{CC}			
Standby current		15.0 μA Max.	ax. 15.0 μA Max.		15.0 μA Max.				
Symmetry	SYM	45 % to 55 %			50 % V _{CC} Level, L_CMOS ≤ 15 pF				
Output voltage	V _{OH}	90 % V _{CC} Min.			Output current*2	I _{OH}	I _{OL}		
Output voltage (DC characteristics)	Va					125 MHz < fo ≤ 170 MHz	-2.0 mA	2.0 mA	
Output load condition	V _{OL} 10 % V _{CC} Wax.				75 MHz ≤ fo ≤ 125 MHz	-1.0 mA	1.0 mA		
Output load condition	L_CMOS	15 pF Max.							
Input voltage	V _{IH}	70 % V _{CC} Min.				Pin 1			
	V _{IL}	30 % V _{CC} Max.				405.444			
Rise/Fall time*2	tr/tf	2.0 ns Max.				125 MHz < fo ≤ 170 MHz 20 % - 80 % V _{CC} , L CMOS = 15 pF			
Output disable time (OE)	tstp oe	2.5 ns Max.			75 MHz ≤ fo ≤ 125 MHz Measured from the time OE o		·		
Output disable time (ST)	tstp_st	1 μs Max.				or measured from the time OF	or ST pin cros	ses 70 % V _{CC}	
Output enable time (OE)	tsta_oe	100 ns + 2 clock cycle Max.				Measured from the time OE pin crosses 70 % V_{CC} or measured from the time \overline{OE} pin crosses 30 % V_{CC}			
Output enable time (ST)	tsta_st	3 ms Max.				Measured from the time \overline{ST} pin crosses 70 % V_{CC} or measured from the time \overline{ST} pin crosses 30 % V_{CC}			
Start-up time	t_str	3 ms Max.				Measured from the time V minimum value, 1.62 V			
Phase Jitter	t _{PJ}	0.3 ps Typ., 0.6 ps Max.				Offset frequency: 12 kHz to 20 MHz			

^{*1} Frequency tolerance includes initial frequency tolerance, temperature variation, supply voltage variation, reflow drift, load drift and aging (+25 °C, 1 year or 10 years). *2 Output current I_{OH}/I_{OL} and Rise/Fall time specifications are dependent on programmed frequency.



Pin description

Pin	Name	I/O type	Function				
OE		l	Outrast Frankla	High [™] or Open: Specified frequency output from OUT pin			
	OE Inpu	Input	Output Enable	Low:	OUT pin is low (pull down with 500 k Ω), only output driver is disabled.		
	ŌĒ	lanut	Output Enable	Low*2 or Open:	Specified frequency output from OUT pin		
		Input		High:	OUT pin is low (pull down with 500 k Ω), only output driver is disabled.		
1	1 ST	Input	Standby	High*1 *3:	Specified frequency output from OUT pin		
				Low:	OUT pin is low (pull down with 500 k Ω), Device goes to standby mode. Supply current reduces to the least as I_std.		
	ST	Input	Standby	Low*2 *3:	Specified frequency output from OUT pin		
				High:	OUT pin is low (pull down with 500 k Ω), Device goes to standby mode. Supply current reduces to the least as I_std.		
2	GND	Power	Ground				
3	OUT	Output	Clock output				
4	V _{CC}	Power	Power supply				

^{*1} If fixing it at High, please connect to V_{CC} directly.

Product Name

 $\frac{\text{SG2016CBA}}{\text{a}} \, \, \frac{\text{156.250000MHz}}{\text{c}} \, \frac{\text{T}}{\text{d}} \, \, \frac{\text{J}}{\text{e}} \, \, \frac{\text{P}}{\text{g}} \, \, \frac{\text{A}}{\text{h}}$

a: Model b: Output (C: CMOS)

c: Frequency d: Supply voltage (T: 1.8 V to 3.3 V Typ.)

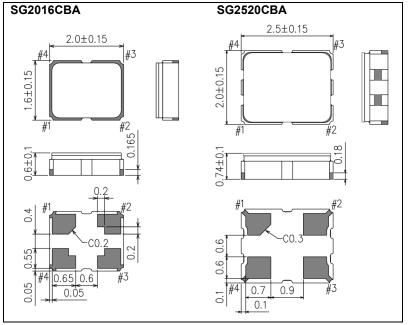
e: Frequency tolerance f: Operating temperature

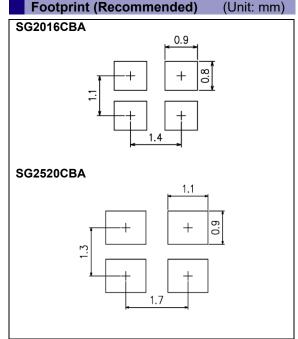
g: Function h: Internal identification code ("A" is default)

e: Frequency tolerance /				
f: Operating temperature				
ВН	±15 × 10 ⁻⁶ / -40 °C to +105 °C			
DJ	±25 x 10 ⁻⁶ / -40 °C to +125 °C			
JJ	±50 x 10 ⁻⁶ / -40 °C to +125 °C			

g: Function		
Р	Output Enable (OE)	
Q	Output Enable (OE)	
S	Standby (ST)	
Т	Standby (ST)	

External dimensions (Unit: mm) SG2016CBA SG2520CBA





■Notes:

In order to achieve optimum jitter performance, the $0.01~\mu F$ to $0.1~\mu F$ capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

^{*2} If fixing it at Low, please connect to GND directly.

^{*3} If necessary to use Open, please select Output Enable function.

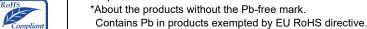
Explanation of the mark that are using it for the catalog



▶Pb free.



▶ Complies with EU RoHS directive.



(Contains Pb in sealing glass, high melting temperature type solder or other.)



▶ Designed for automotive general equipment.



▶ Designed for automotive applications related to driving and safety.

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